



#### RE470

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Pitch 0.40 mm (15.7mil) and 0.50 mm (19.7 mil.)
- Adaption board for 23 different SMD-QFP s
- Hole diameter 1.00 mm
- Prescratched rated break point for the separation of individual modules from the board
- Gerber data for manufacture of the solder resist masks and the soldering paste imprint will be provided free of charge on request
- Size 132 x 203 mm

| Module-No. | Pitch      | Pin          | mil  | Size (mm)                    |
|------------|------------|--------------|------|------------------------------|
| RE470-01   | S 0.500 mm | QFP 40, 48   | 19.7 | 7.00 x 7.00                  |
|            | S 0.400 mm | QFP 80       | 15.7 | 10,00 x 10,00                |
| RE470-02   | S 0.500 mm | QFP 80       | 19.7 | 12,00 x 12,00                |
|            | S 0.400 mm | QFP 100, 108 | 15.7 | 12,00 x 12,00                |
| RE470-03   | R 0.500 mm | QFP 120, 128 | 19.7 | 14,00 x 20,00                |
|            | R 0.400 mm | QFP 100, 108 | 15.7 | 10,00 x 14,00                |
| RE470-04   | S 0.500 mm | QFP 72, 100  | 19.7 | 10,00 x 10,00                |
|            | S 0.400 mm | QFP 12       | 15.7 | 14,00 x 14,00                |
| RE470-05   | S 0.500 mm | QFP 144, 176 | 19.7 | 20,00 x 20,00, 24,00 x 24,00 |
|            | S 0.400 mm | QFP 184      | 15.7 | 20,00 x 20,00                |
| RE470-06   | R 0.500 mm | QFP 256, 264 | 19.7 | 28,00 x 40,00                |
|            | R 0.400 mm | QFP 224, 232 | 15.7 | 20,00 x 28,00                |
| RE470-07   | S 0.500 mm | QFP 208, 240 | 19.7 | 28,00 x 28,00, 32,00 x 32,00 |
|            | S 0.400 mm | QFP 264      | 15.7 | 28,00 x 28,00                |